

Amendments to the Claims

Please amend the following claims as indicated.
Added text has been underlined, deleted text has been struck through. All amendments are supported by the originally-filed application.

1. (currently amended) A low-profile carrier for temporarily mounting a non-wafer form device comprising:

a test ring holder configured to hold said non-wafer form device, said test ring holder having a first face and a second face, said second face of said test ring holder configured to be bonded to a mechanical support base;

a test ring magnet configured to be mounted substantially within a first recess formed within said first face of said test ring holder;

a second recess formed within said first face of said test ring holder and circumscribed within said first recess, said second recess forming a mounting location for said non-wafer form device; and

a test ring cover configured to be mounted in said first recess and held magnetically in a location proximate to said test ring holder, a combined thickness of the test ring holder and the mechanical support base not exceeding 1270 microns.

2. (original) The low-profile carrier of claim 1 wherein said test ring magnet is mounted to said test ring holder by an adhesive.

3. (original) The low-profile carrier of claim 1 wherein said mechanical support base is about 280 microns in thickness.

4. (cancelled)

5. (original) The low-profile carrier of claim 1 wherein said test ring holder is fabricated from an alkali-free glass cloth impregnated with resin.

6. (original) The low-profile carrier of claim 1 wherein said test ring holder is fabricated from polyimide.

7. (original) The low-profile carrier of claim 1 wherein said first and second recesses have a depth sufficient to mount both said test ring magnet and said test ring cover in such a way as to be substantially coplanar with or below a non-recessed portion of said first face.

8. (currently amended) A low-profile carrier for temporarily mounting a non-wafer form device comprising:

a test ring holder configured to hold said non-wafer form device, said test ring having a first face and a second face, said second face configured to be mechanically coupled to a support base;

a test ring cover configured to be held magnetically in a location proximate to said test ring holder and to be mounted substantially within a first recess formed with said first face of said test ring holder; and

a second recess formed within said first face of said test ring holder and circumscribed within said first recess, said second recess forming a mounting location for said non-wafer form device, at least one of the test ring cover or the test ring holder being formed from a permanently magnetic material.

9. (cancelled)

10. (cancelled)

11. (cancelled)

12. (original) The low-profile carrier of claim 8 wherein said test ring holder is formed with a thru-hole circumscribed within said second recess.

13. (original) A low-profile carrier for temporarily mounting a non-wafer form device comprising:

 a test ring holder configured to hold said non-wafer form device, said test ring having a first face and a second face, said second face of said test ring holder configured to be mechanically coupled to a support base;

 a test ring cover configured to be held magnetically in a location proximate to said test ring holder and to be mounted substantially within a first recess formed within said first face of said test ring holder;

 a second recess formed within said first face of said test ring holder and circumscribed within said first recess, said second recess forming a mounting location for said non-wafer form device;

 a thru-hole formed within said test ring holder and circumscribed within said second recess; and

 an insert configured to be mounted within said thru-hole and in communication with said support base.

14. (original) The low-profile carrier of claim 13 wherein said test ring cover is formed from a permanently magnetic material.

15. (original) The low-profile carrier of claim 13 wherein said insert is formed from a permanently magnetic material.

16. (original) The low-profile carrier of claim 13 wherein both said test ring cover and said insert are formed from a permanently magnetic material.

17. (original) The low-profile carrier of claim 13 wherein said insert is formed with a thru-hole.

18. (currently amended) A low-profile carrier adapter for temporarily mounting a non-wafer form device comprising:

a means for holding said non-wafer form device, said holding means having a first face and a second face, said second face of said ~~test ring holder~~ holding means configured to be mechanically coupled to a support base;

a means for covering said non-wafer form device, said covering means configured to be held magnetically in a location proximate to said holding means and to be mounted within a first recess formed within said first face of said holding means; and

a second recess formed within said first face of said holding means and circumscribed within said first recess, said second recess forming a mounting location for said non-wafer form device, at least one of the holding means or the covering means being formed from a permanently magnetic material.